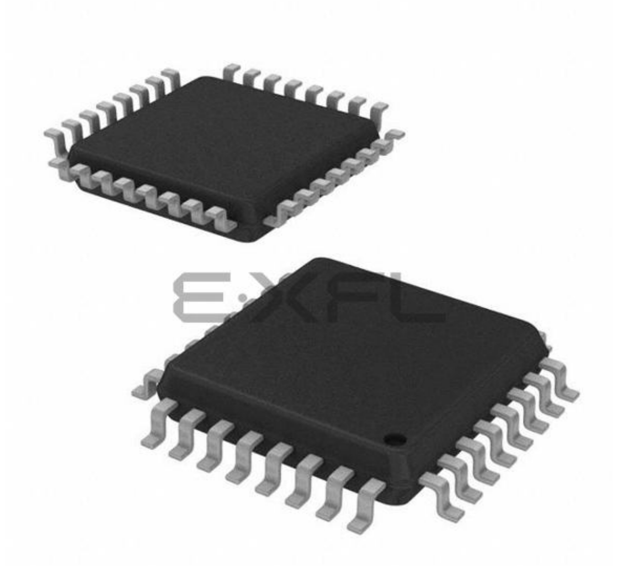

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f324k6ta

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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6.2 MULTI-OSCILLATOR (MO)

The main clock of the ST7 can be generated by three different source types coming from the multi-oscillator block:

- an external source
- 4 crystal or ceramic resonator oscillators
- an internal high frequency RC oscillator

Each oscillator is optimized for a given frequency range in terms of consumption and is selectable through the option byte. The associated hardware configurations are shown in Table 5. Refer to the electrical characteristics section for more details.

Caution: The OSC1 and/or OSC2 pins must not be left unconnected. For the purposes of Failure Mode and Effect Analysis, it should be noted that if the OSC1 and/or OSC2 pins are left unconnected, the ST7 main oscillator may start and, in this configuration, could generate an f_{OSC} clock frequency in excess of the allowed maximum (>16MHz.), putting the ST7 in an unsafe/undefined state. The product behaviour must therefore be considered undefined when the OSC pins are left unconnected.

External Clock Source

In this external clock mode, a clock signal (square, sinus or triangle) with ~50% duty cycle has to drive the OSC1 pin while the OSC2 pin is tied to ground.

Crystal/Ceramic Oscillators

This family of oscillators has the advantage of producing a very accurate rate on the main clock of the ST7. The selection within a list of 4 oscillators with different frequency ranges has to be done by option byte in order to reduce consumption (refer to Section 14.1 on page 150 for more details on the frequency ranges). In this mode of the multi-oscillator, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and start-up stabilization time. The loading capacitance values must be adjusted according to the selected oscillator.

These oscillators are not stopped during the RESET phase to avoid losing time in the oscillator start-up phase.

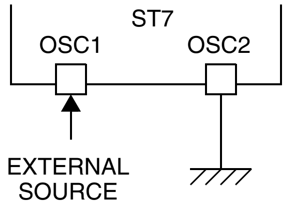
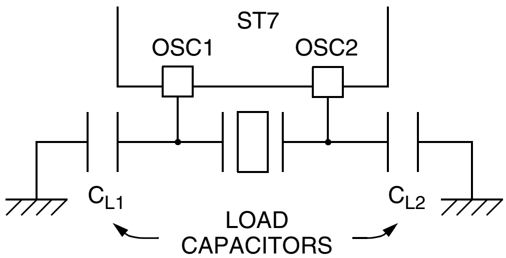
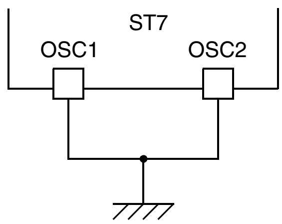
Internal RC Oscillator

This oscillator allows a low cost solution for the main clock of the ST7 using only an internal resistor and capacitor. Internal RC oscillator mode has the drawback of a lower frequency accuracy and should not be used in applications that require accurate timing.

In this mode, the two oscillator pins have to be tied to ground.

In order not to exceed the max. operating frequency, the internal RC oscillator must not be used with the PLL.

Table 5. ST7 Clock Sources

	Hardware Configuration
External Clock	
Crystal/Ceramic Resonators	
Internal RC Oscillator	

INTERRUPTS (Cont'd)

Table 8. Interrupt Mapping

N°	Source Block	Description	Register Label	Priority Order	Exit from HALT/ ACTIVE HALT[1)]	Address Vector
	RESET	Reset	N/A		yes	FFFEh-FFFFh
	TRAP	Software interrupt			no	FFFCh-FFFDh
0	Not used					FFFAh-FFFBh
1	MCC/RTC	Main clock controller time base interrupt	MCCSR	Higher Priority	yes	FFF8h-FFF9h
2	ei0	External interrupt port A3..0	N/A		yes	FFF6h-FFF7h
3	ei1	External interrupt port F2..0			yes	FFF4h-FFF5h
4	ei2	External interrupt port B3..0			yes	FFF2h-FFF3h
5	ei3	External interrupt port B7..4			yes	FFF0h-FFF1h
6	Not used					FFEEh-FFEFh
7	SPI	SPI peripheral interrupts	SPICSR	↓	yes	FFECh-FFEDh
8	TIMER A	TIMER A peripheral interrupts	TASR		no	FFEAh-FFEBh
9	TIMER B	TIMER B peripheral interrupts	TBSR		no	FFE8h-FFE9h
10	SCI	SCI Peripheral interrupts	SCISR	Lower Priority	no	FFE6h-FFE7h
11	AVD	Auxiliary Voltage detector interrupt	SICSR		no	FFE4h-FFE5h

Notes:
1. In Flash devices only a RESET or MCC/RTC interrupt can be used to wake-up from Active Halt mode.

7.6 EXTERNAL INTERRUPTS

7.6.1 I/O Port Interrupt Sensitivity

The external interrupt sensitivity is controlled by the IPA, IPB and ISxx bits of the EICR register (Figure 21). This control allows to have up to 4 fully independent external interrupt source sensitivities.

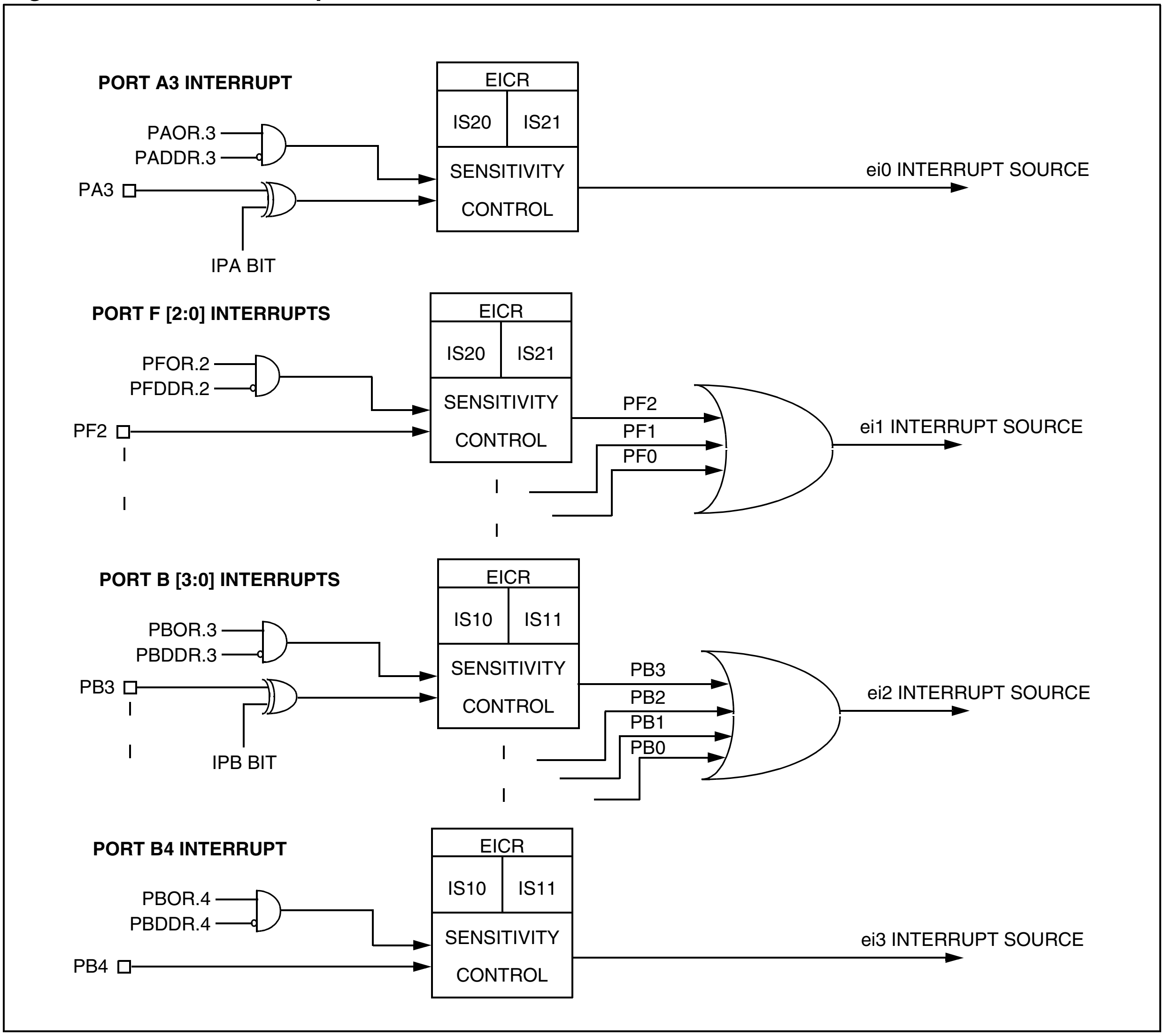
Each external interrupt source can be generated on four (or five) different events on the pin:

- Falling edge
- Rising edge
- Falling and rising edge
- Falling edge and low level
- Rising edge and high level (only for ei0 and ei2)

To guarantee correct functionality, the sensitivity bits in the EICR register can be modified only when the I1 and I0 bits of the CC register are both set to 1 (level 3). This means that interrupts must be disabled before changing sensitivity.

The pending interrupts are cleared by writing a different value in the ISx[1:0], IPA or IPB bits of the EICR.

Figure 21. External Interrupt Control bits



I/O PORTS (Cont'd)

Figure 29. I/O Port General Block Diagram

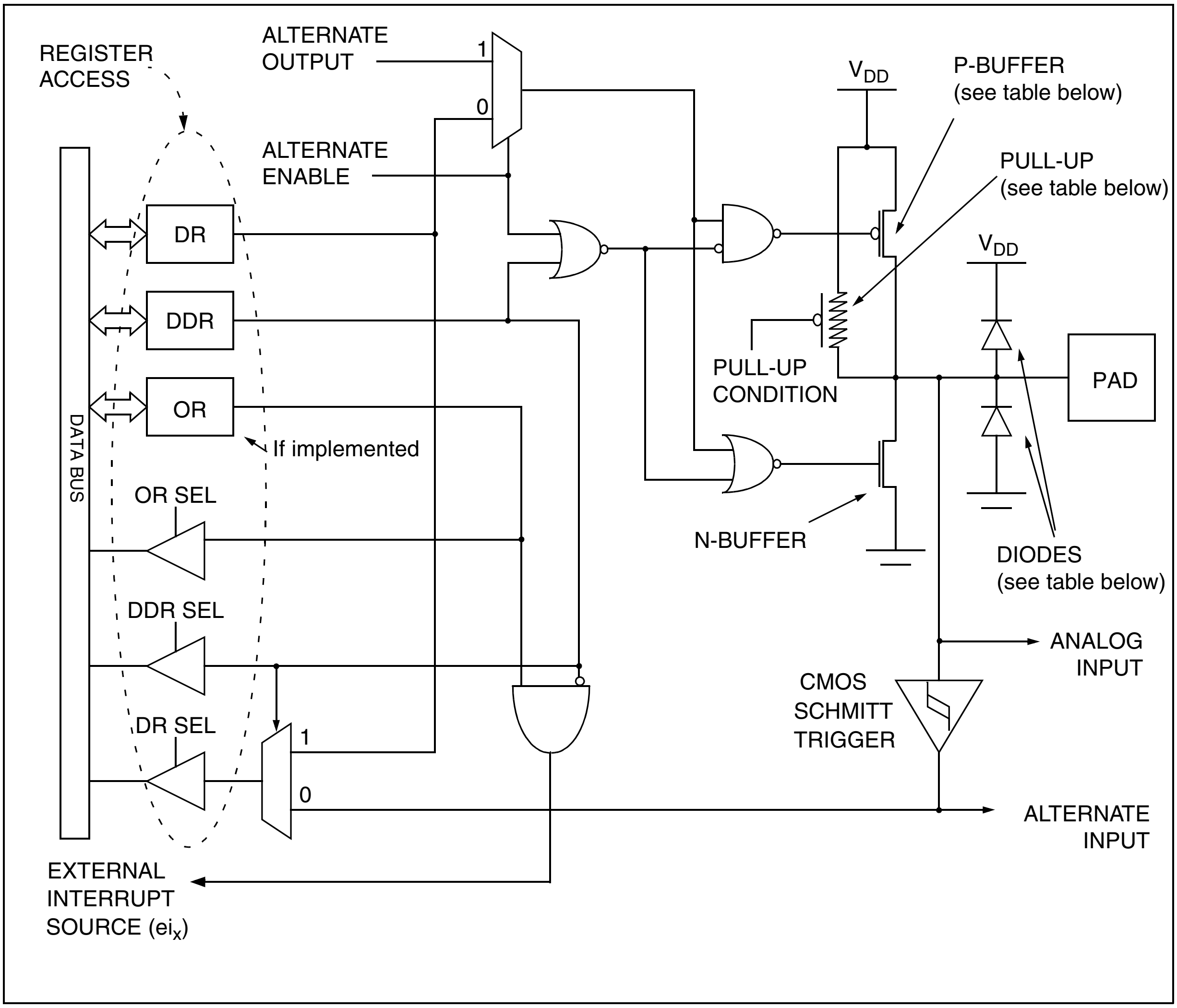


Table 10. I/O Port Mode Options

Configuration Mode		Pull-Up	P-Buffer	Diodes	
				to V_{DD}	to V_{SS}
Input	Floating with/without Interrupt	Off	Off	On	On
	Pull-up with/without Interrupt	On			
Output	Push-pull	Off	On		
	Open Drain (logic level)		Off		
	True Open Drain	NI	NI	NI (see note)	

Legend: NI - not implemented
Off - implemented not activated
On - implemented and activated

Note: The diode to V_{DD} is not implemented in the true open drain pads. A local protection between the pad and V_{SS} is implemented to protect the device against positive stress.

I/O PORTS (Cont'd)

CAUTION: The alternate function must not be activated as long as the pin is configured as input with interrupt, in order to avoid generating spurious interrupts.

Analog alternate function

When the pin is used as an ADC input, the I/O must be configured as floating input. The analog multiplexer (controlled by the ADC registers) switches the analog voltage present on the selected pin to the common analog rail which is connected to the ADC input.

It is recommended not to change the voltage level or loading on any port pin while conversion is in progress. Furthermore it is recommended not to have clocking pins located close to a selected analog pin.

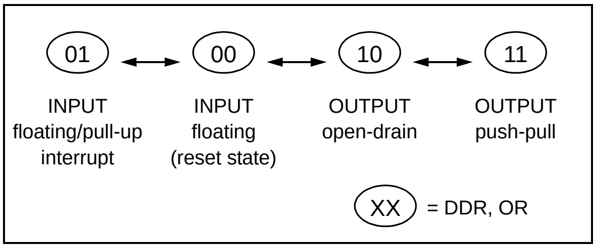
WARNING: The analog input voltage level must be within the limits stated in the absolute maximum ratings.

9.3 I/O PORT IMPLEMENTATION

The hardware implementation on each I/O port depends on the settings in the DDR and OR registers and specific feature of the I/O port such as ADC Input or true open drain.

Switching these I/O ports from one state to another should be done in a sequence that prevents unwanted side effects. Recommended safe transitions are illustrated in Figure 30 Other transitions are potentially risky and should be avoided, since they are likely to present unwanted side-effects such as spurious interrupt generation.

Figure 30. Interrupt I/O Port State Transitions



9.4 LOW POWER MODES

Mode	Description
WAIT	No effect on I/O ports. External interrupts cause the device to exit from WAIT mode.
HALT	No effect on I/O ports. External interrupts cause the device to exit from HALT mode.

9.5 INTERRUPTS

The external interrupt event generates an interrupt if the corresponding configuration is selected with DDR and OR registers and the interrupt mask in the CC register is not active (RIM instruction).

Interrupt Event	Event Flag	Enable Control Bit	Exit from Wait	Exit from Halt
External interrupt on selected external event	-	DDRx ORx	Yes	Yes

10-BIT A/D CONVERTER (ADC) (Cont'd)

10.6.6 Register Description

CONTROL/STATUS REGISTER (ADCCSR)

Read/Write (Except bit 7 read only)

Reset Value: 0000 0000 (00h)

7							0
EOC	SPEED	ADON	0	CH3	CH2	CH1	CH0

Bit 7 = **EOC** *End of Conversion*
This bit is set by hardware. It is cleared by hardware when software reads the ADCDRH register or writes to any bit of the ADCCSR register.
0: Conversion is not complete
1: Conversion complete

Bit 6 = **SPEED** *ADC clock selection*
This bit is set and cleared by software.
0: $f_{ADC} = f_{CPU}/4$
1: $f_{ADC} = f_{CPU}/2$

Bit 5 = **ADON** *A/D Converter on*
This bit is set and cleared by software.
0: Disable ADC and stop conversion
1: Enable ADC and start conversion

Bit 4 = **Reserved.** Must be kept cleared.

Bit 3:0 = **CH[3:0]** *Channel Selection*
These bits are set and cleared by software. They select the analog input to convert.

Channel Pin*	CH3	CH2	CH1	CH0
AIN0	0	0	0	0
AIN1	0	0	0	1
AIN2	0	0	1	0
AIN3	0	0	1	1
AIN4	0	1	0	0
AIN5	0	1	0	1
AIN6	0	1	1	0
AIN7	0	1	1	1
AIN8	1	0	0	0
AIN9	1	0	0	1
AIN10	1	0	1	0
AIN11	1	0	1	1
AIN12	1	1	0	0
AIN13	1	1	0	1
AIN14	1	1	1	0
AIN15	1	1	1	1

*The number of channels is device dependent. Refer to the device pinout description.

DATA REGISTER (ADCDRH)

Read Only

Reset Value: 0000 0000 (00h)

7							0
D9	D8	D7	D6	D5	D4	D3	D2

Bit 7:0 = **D[9:2]** *MSB of Converted Analog Value*

DATA REGISTER (ADCDRL)

Read Only

Reset Value: 0000 0000 (00h)

7							0
0	0	0	0	0	0	D1	D0

Bit 7:2 = Reserved. Forced by hardware to 0.

Bit 1:0 = **D[1:0]** *LSB of Converted Analog Value*

12.6 CLOCK AND TIMING CHARACTERISTICS

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A.

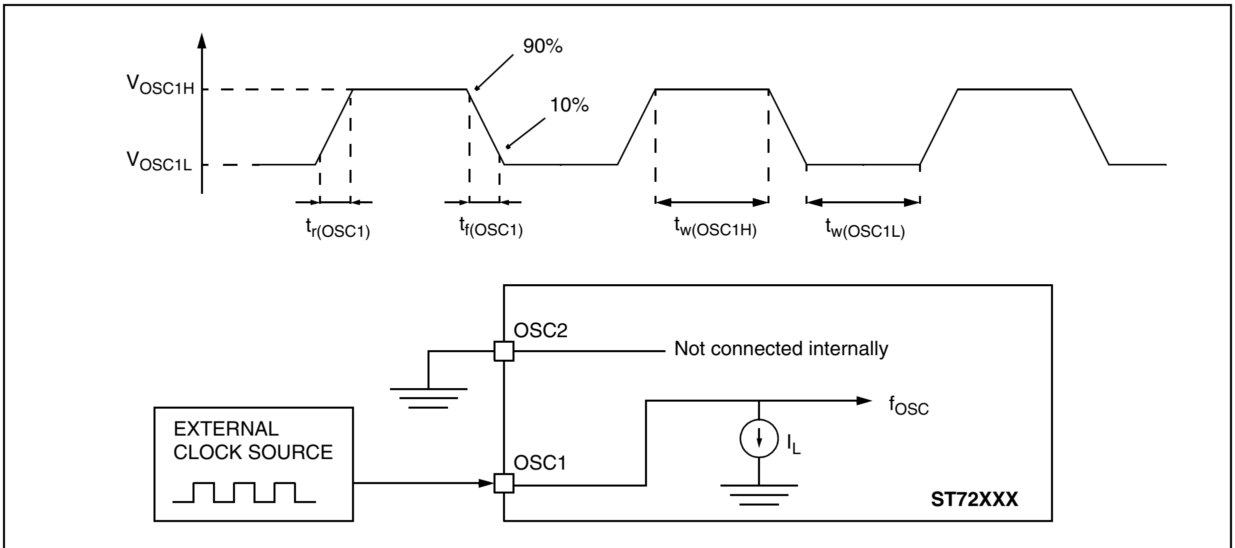
12.6.1 General Timings

Symbol	Parameter	Conditions	Min	Typ [1]	Max	Unit
$t_{c(INST)}$	Instruction cycle time		2	3	12	t_{CPU}
		f_{CPU}=8MHz	250	375	1500	ns
$t_{v(IT)}$	Interrupt reaction time [2] $t_{v(IT)} = \Delta t_{c(INST)} + 10$		10		22	t_{CPU}
		f_{CPU}=8MHz	1.25		2.75	µs

12.6.2 External Clock Source

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OSC1H}	OSC1 input pin high level voltage	see Figure 65	V_{DD}-1		V_{DD}	V
V_{OSC1L}	OSC1 input pin low level voltage		V_{SS}		V_{SS}+1	
$t_{w(OSC1H)}$ $t_{w(OSC1L)}$	OSC1 high or low time [3]		5			ns
$t_{r(OSC1)}$ $t_{f(OSC1)}$	OSC1 rise or fall time [3]				15	
I_L	OSC1 Input leakage current	$V_{SS} \le V_{IN} \le V_{DD}$			±1	µA

Figure 65. Typical Application with an External Clock Source



Notes:

1. Data based on typical application software.
2. Time measured between interrupt event and interrupt vector fetch. $\Delta t_{c(INST)}$ is the number of t_{CPU} cycles needed to finish the current instruction execution.
3. Data based on design simulation and/or technology characteristics, not tested in production.

EMC CHARACTERISTICS (Cont'd)

12.8.3 Absolute Maximum Ratings (Electrical Sensitivity)

Based on three different tests (ESD, LU and DLU) using specific measurement methods, the product is stressed in order to determine its performance in terms of electrical sensitivity. For more details, refer to the application note AN1181.

12.8.3.1 Electro-Static Discharge (ESD)

Electro-Static Discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts*(n+1) supply pin). Two models can be simulated: Human Body Model and Machine Model. This test conforms to the JESD22-A114A/A115A standard.

Absolute Maximum Ratings

Symbol	Ratings	Conditions	Maximum value [1]	Unit
$V_{ESD(HBM)}$	Electro-static discharge voltage (Human Body Model)	T_A=+25°C	2000	V
$V_{ESD(MM)}$	Electro-static discharge voltage (Machine Model)	T_A=+25°C	200	
$V_{ESD(CD)}$	Electro-static discharge voltage (Charged Device Model)	T_A=+25°C	250	

Notes:
1. Data based on characterization results, not tested in production.

12.8.3.2 Static and Dynamic Latch-Up

- **LU**: 3 complementary static tests are required on 10 parts to assess the latch-up performance. A supply overvoltage (applied to each power supply pin) and a current injection (applied to each input, output and configurable I/O pin) are performed on each sample. This test conforms to the EIA/JESD 78 IC latch-up standard. For more details, refer to the application note AN1181.
- **DLU**: Electro-Static Discharges (one positive then one negative test) are applied to each pin of 3 samples when the micro is running to assess the latch-up performance in dynamic mode. Power supplies are set to the typical values, the oscillator is connected as near as possible to the pins of the micro and the component is put in reset mode. This test conforms to the IEC1000-4-2 and SAEJ1752/3 standards. For more details, refer to the application note AN1181.

Electrical Sensitivities

Symbol	Parameter	Conditions	Class [1]
LU	Static latch-up class	T_A=+25°C T_A=+85°C T_A=+125°C	A A A
DLU	Dynamic latch-up class	V_{DD}=5.5V, f_{OSC}=4MHz, T_A=+25°C	A

Notes:
1. Class description: A Class is an STMicroelectronics internal specification. All its limits are higher than the JEDEC specifications, that means when a device belongs to Class A it exceeds the JEDEC standard. B Class strictly covers all the JEDEC criteria (international standard).

I/O PORT PIN CHARACTERISTICS (Cont'd)

Figure 74. Typical V_{OL} vs. V_{DD} (std. ports)

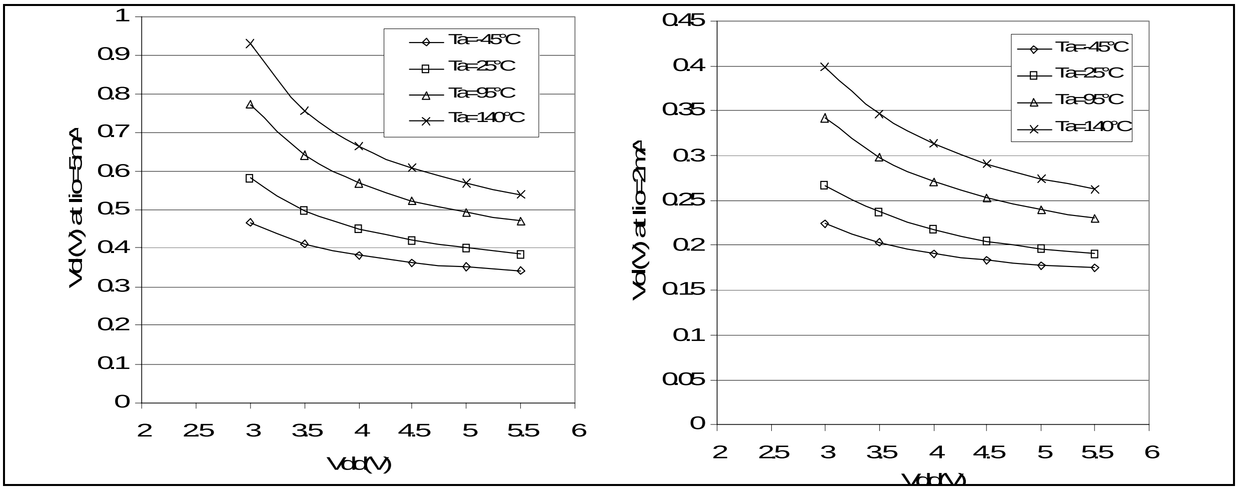


Figure 75. Typical V_{OL} vs. V_{DD} (high-sink ports)

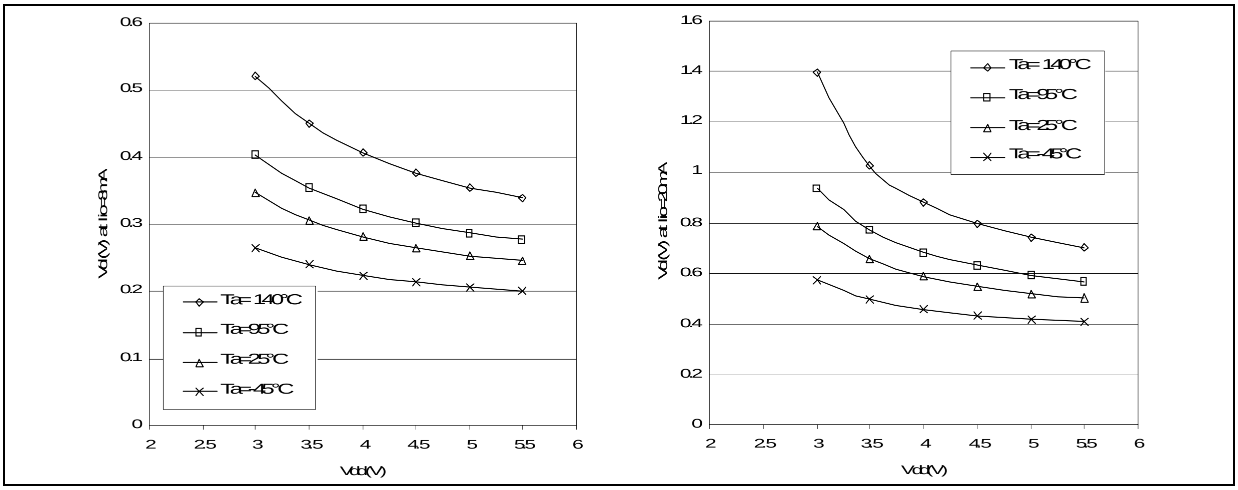
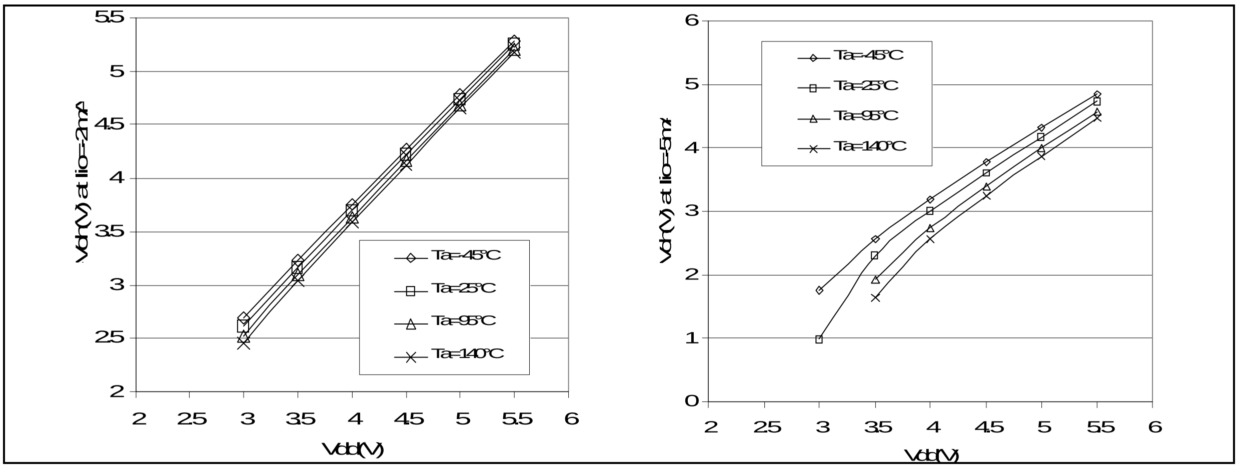


Figure 76. Typical V_{OH} vs. V_{DD}



12.13 10-BIT ADC CHARACTERISTICS

Subject to general operating conditions for V_{DD}, f_{CPU}, and T_A unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{ADC}	ADC clock frequency		0.4		2	MHz
V_{AREF}	Analog reference voltage	$0.7*V_{DD} \leq V_{AREF} \leq V_{DD}$	3.8		V_{DD}	V
V_{AIN}	Conversion voltage range [1]		V_{SSA}		V_{AREF}	
I_{lkg}	Positive input leakage current for analog input[2]	$-40°C \leq T_A \leq +85°C$			±250	nA
		$+85°C \leq T_A \leq +125°C$			±1	µA
R_{AIN}	External input impedance				see Figure 83 and Figure 84[2)3)4)]	kΩ
C_{AIN}	External capacitor on analog input					pF
f_{AIN}	Variation freq. of analog input signal					Hz
C_{ADC}	Internal sample and hold capacitor			12		pF
t_{ADC}	Conversion time (Sample+Hold) f_{CPU}=8MHz, SPEED=0 f_{ADC}=2MHz		7.5			µs
t_{ADC}	- No of sample capacitor loading cycles - No. of Hold conversion cycles		4 11			$1/f_{ADC}$

Notes:

1. Any added external serial resistor will downgrade the ADC accuracy (especially for resistance greater than 10kΩ). Data based on characterization results, not tested in production.

2.For Flash devices: injecting negative current on any of the analog input pins significantly reduces the accuracy of any conversion being performed on any analog input. Analog pins of ST72F324 devices can be protected against negative injection by adding a Schottky diode (pin to ground). Injecting negative current on digital input pins degrades ADC accuracy especially if performed on a pin close to the analog input pins. Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in Section 12.9 does not affect the ADC accuracy.

15 KNOWN LIMITATIONS

15.1 ALL DEVICES

15.1.1 External RC option

The External RC clock source option described in previous datasheet revisions is no longer supported and has been removed from this specification.

15.1.2 CSS Function

The Clock Security System function has been removed from the datasheet.

15.1.3 Safe Connection of OSC1/OSC2 Pins

The OSC1 and/or OSC2 pins must not be left unconnected otherwise the ST7 main oscillator may start and, in this configuration, could generate an f_{OSC} clock frequency in excess of the allowed maximum (>16MHz.), putting the ST7 in an unsafe/undefined state. Refer to Section 6.2 on page 24.

15.1.4 Unexpected Reset Fetch

If an interrupt request occurs while a “POP CC” instruction is executed, the interrupt controller does not recognise the source of the interrupt and, by default, passes the RESET vector address to the CPU.

Workaround

To solve this issue, a “POP CC” instruction must always be preceded by a “SIM” instruction.

15.1.5 Clearing active interrupts outside interrupt routine

When an active interrupt request occurs at the same time as the related flag is being cleared, an unwanted reset may occur.

Note: clearing the related interrupt mask will not generate an unwanted reset

Concurrent interrupt context

The symptom does not occur when the interrupts are handled normally, i.e.

when:

– The interrupt flag is cleared within its own interrupt routine

– The interrupt flag is cleared within any interrupt routine

– The interrupt flag is cleared in any part of the code while this interrupt is disabled

If these conditions are not met, the symptom can be avoided by implementing the following sequence:

Perform SIM and RIM operation before and after resetting an active interrupt request.

Example:

SIM

reset interrupt flag

RIM

Nested interrupt context:

The symptom does not occur when the interrupts are handled normally, i.e.

when:

– The interrupt flag is cleared within its own interrupt routine

– The interrupt flag is cleared within any interrupt routine with higher or identical priority level

– The interrupt flag is cleared in any part of the code while this interrupt is disabled

If these conditions are not met, the symptom can be avoided by implementing the following sequence:

PUSH CC

SIM

reset interrupt flag

POP CC

15.1.6 External Interrupt Missed

To avoid any risk of generating a parasitic interrupt, the edge detector is automatically disabled for one clock cycle during an access to either DDR and OR. Any input signal edge during this period will not be detected and will not generate an interrupt.

This case can typically occur if the application refreshes the port configuration registers at intervals during runtime.

Workaround

The workaround is based on software checking the level on the interrupt pin before and after writing to the PxOR or PxDDR registers. If there is a level change (depending on the sensitivity programmed for this pin) the interrupt routine is invoked using the call instruction with three extra PUSH instructions before executing the interrupt routine (this is to make the call compatible with the IRET instruction at the end of the interrupt service routine).

But detection of the level change does ensure that edge occurs during the critical 1 cycle duration and the interrupt has been missed. This may lead to occurrence of same interrupt twice (one hardware and another with software call).